ABSTRACT

A method for manufacturing an electronic device includes a step of preparing a structure (100) including a pressure-sensitive adhesive film (50) including a pressure-sensitive adhesive resin layer (A), a base material layer (10), and a pressure-sensitive adhesive resin layer (B) in this order, an electronic component (70) on a pressure-sensitive adhesive resin layer (A) side of the pressure-sensitive adhesive film (50), and a support substrate (80) on a pressure-sensitive adhesive resin layer (B) side of the pressure-sensitive adhesive film (50); and a step of peeling the support substrate (80) from the structure (100) by reducing an adhesive strength of the pressure-sensitive adhesive resin layer (B) by a heating treatment, in which the support substrate (80) includes a stainless steel substrate having an oxide film on a surface.